

Appl. No. 09/943,203
Amdt. Dated August 25, 2004
Reply to Office action of June 2, 2004
Attorney Docket No. P13514-US1
EUS/J/P/04-2084

Amendments to the Claims:

This listing of claims replaces all prior versions, and listings, of claims in the application:

Listing of Claims:

1-36. (Cancelled)

37. (Currently Amended) A process of forming an encapsulated circuit board arrangement having at least one layer of tracks, the encapsulated circuit board arrangement having a first side as an interface side and a second side as a protective cover, the process comprising the steps of:

applying at least one layer of ~~sequentially processed~~ tracks on a first side of an interface carrier, a second side of the interface carrier being an interface side of the encapsulated circuit board arrangement; and

applying an adhesive layer on top of the last applied layer of tracks; and

joining a last applied sequentially processed layer to a support carrier with an to said adhesive layer, said adhesive layer being intermediate to and coupling said interface carrier and said support carrier, the support carrier forming the protective cover [[of]] on the second side of the encapsulated circuit board arrangement.

38-39. (Cancelled).

40. (Currently Amended) The process according to claim 37, wherein at least one of the at least one ~~sequentially processed~~ layer of tracks is applied using offset printing technology.

41. (Currently Amended) The process according to claim 40, wherein the step of applying at least one layer of ~~sequentially processed~~ tracks comprises the step of applying an acrylate as a dielectric ~~of at least one of the at least one sequentially processed layer.~~

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42. (Currently Amended) The process according to claim ~~[[38]]~~ 37, wherein the adhesive layer is applied using offset printing technology.

43. (Currently Amended) The process according to claim 37, wherein the ~~step of joining the last applied sequentially processed layer to a~~ support carrier comprises the ~~step of joining the last applied sequentially processed layer to a support~~ carrier which is at least a part of a cover of a housing in which the encapsulated circuit board arrangement is mounted.

44. (Currently Amended) The process according to claim 37, wherein the ~~step of joining the last applied sequentially processed layer to a~~ support carrier comprises the ~~step of joining the last applied sequentially processed layer to a support~~ carrier which is at least a part of an enclosure on in which the encapsulated circuit board arrangement is mounted.

45. (Currently Amended) The process according to claim 37, wherein the ~~step of joining the last applied sequentially processed layer to a~~ support carrier comprises the ~~step of joining the last applied sequentially processed layer to a support~~ carrier which is rigid.

46. (Currently Amended) The process according to claim 37, wherein the ~~step of joining the last applied sequentially processed layer to a~~ support carrier comprises the ~~step of joining the last applied sequentially processed layer to a support~~ carrier which is bendable.

47. (Currently Amended) The process according to claim 37, wherein the ~~step of applying at least one layer of sequentially processed tracks~~ comprises the ~~step of applying at least one sequentially processed layer having connection circuitry.~~

48-49. (Cancelled).

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50. (Currently Amended) The process according to claim 37, wherein the ~~at least one layer of sequentially processed tracks is applied to an interface layer having~~ carrier comprises at least one via.

51. (Currently Amended) The process according to claim 37, wherein the ~~at least one layer of sequentially processed tracks is applied to an interface layer having~~ carrier comprises at least one solid via.

52. (Currently Amended) The process according to claim 37, wherein the ~~at least one layer of sequentially processed tracks is applied to an interface~~ carrier layer that is bendable.

53. (Currently Amended) The process according to claim 37, wherein the ~~at least one layer of sequentially processed tracks is applied to an interface~~ carrier layer that is made of polyimide.

54-72. (Cancelled)

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